

Serial No. 10/615,432  
Response dated July 23, 2004  
Reply to Office Action of May 4, 2004

Docket No. 5000-5108

**IN THE ABSTRACT**

Please amend the abstract of the disclosure as follows:

A radiator system includes a high-temperature body being a thermal source, a receiver with the high-temperature body boarded thereon, and a thermal buffer. The receiver receives heat from the high-temperature body. The thermal buffer is interposed ~~at least~~ between the high-temperature body and the receiver ~~to buffer~~ buffering thermal transmission from the high-temperature body to the receiver, includes a high thermal conductor and a low expander disposed ~~at a position~~ facing the high-temperature body and buried in the high thermal conductor, and has a first bonding area with respect to the high-temperature body and a second bonding area, larger than the first, with respect to the receiver. ~~The second bonding area is enlarged greater than the first bonding area.~~ The heat from the high-temperature body is radiated ~~by the receiver or is radiated~~ by way of the receiver. Thus, the thermal expansion difference can be minimized between the high-temperature body and receiver.